AFE4960 Two-Channel ECG, Respiration and Pace Pulse Detection Analog Front End (AFE) for Clinical Wearables

1 Features

• Supports ECG and respiration impedance measurement; configurable as 2-channel ECG or 1-channel ECG + 1-channel Respiration
• 222 μA/channel while operating as 2-channel ECG
• Integrated Pace pulse detection on 1 channel
• Supports a 3-lead ECG, extendable to 5 leads or higher by operating two or more AFEs in parallel
• ECG signal chain:
  – Single channel ECG acquisition up to 2.048 kHz
  – 2 channel ECG acquisition up to 1.36 kHz/channel
  – RLD output to set body bias through third electrode
  – Programmable INA gain from 2~12
  – >1 GΩ input impedance, CMRR > 100 dB
  – Input noise (0.5-150 Hz): 13 µVpp at INA gain of 3; 5 µVpp at INA gain of 12
  – Integrated 370 Hz anti-aliasing low pass filter
  – Mode for Continuous lead on/off detection
  – Mode for Lead impedance measurement
• Bio-Z signal chain:
  – Measurement of Bio-impedance over excitation frequency from 30 kHz to 100 kHz
  – Sine wave or square wave excitation
  – Respiration impedance measurement: 45 mΩ-p peak noise on a baseline impedance of 2 kΩ
• Dual channel ECG channel:
  – Bio-Z receiver configurable as a 2nd ECG channel
• External clock and internal oscillator modes
• FIFO with 128-sample Depth, 24-bit word
• SPI™, I2C interfaces: Selectable by pin
• 2.6-mm × 2.6-mm DSBGA, 0.4-mm Pitch
• Supplies: Rx:1.7-1.9 V, IO:1.7-1.9 V

3 Description

The AFE4960 can be configured as either a 2-channel ECG receiver or as a 1-channel ECG receiver and a respiration impedance channel. The AFE signal chains can interface in a flexible manner to up to 4 electrodes. A right leg drive (RLD) amplifier output, can be used to set the body bias. The AFE has DC lead biasing for lead on/off detection, and AC lead biasing for measuring the lead impedance. Pacemaker pulse detection is supported on one channel.

All the signal chain outputs are converted by a single ADC in well-defined time slots and stored as 24-bit words in a 128-sample FIFO which can be read out using a SPI or an I2C interface.

The AFE4960 is a fully integrated solution to realize a 3-lead ECG system. Synchronized operation of two AFEs in parallel can be used to realize a 5-lead ECG.

Device Information

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>PACKAGE(1)</th>
<th>BODY SIZE (NOM)</th>
</tr>
</thead>
<tbody>
<tr>
<td>AFE4960</td>
<td>DSBGA (YBG 36)</td>
<td>2.6 mm x 2.6 mm</td>
</tr>
</tbody>
</table>

(1) For all available packages, see the orderable addendum at the end of the data sheet.

2 Applications

• Wireless patches for in-patient and out-patient monitoring
• Event monitors for arrhythmia detection
• Hand-held ECG monitor
• Portable multi-lead ECG
• Patient vital sign monitoring: holter, event, stress and telemedicine

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.
4 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

4.1 Documentation Support

4.1.1 Related Documentation

For related documentation, see the following:

- AFE4960 EVM User’s Guide, SBAU385
- Analog Front End for 3-Lead and 5-Lead ECG, SBAA536
- 5-Lead ECG Application Report, SBAA523

These documents are available upon request.

4.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on Subscribe to updates to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

4.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

4.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

4.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

4.6 Glossary

TI Glossary
This glossary lists and explains terms, acronyms, and definitions.

5 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.
## PACKAGING INFORMATION

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<tr>
<th>Orderable Device</th>
<th>Status</th>
<th>Package Type</th>
<th>Pins</th>
<th>Package Qty</th>
<th>Eco Plan</th>
<th>Lead finish/ Ball material</th>
<th>MSL Peak Temp</th>
<th>Op Temp (°C)</th>
<th>Device Marking</th>
<th>Samples</th>
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<tr>
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(1) The marketing status values are defined as follows:
- **ACTIVE**: Product device recommended for new designs.
- **LIFEBUY**: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
- **NRND**: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
- **PREVIEW**: Device has been announced but is not in production. Samples may or may not be available.
- ** OBSOLETE**: TI has discontinued the production of the device.

(2) **RoHS**: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt**: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green**: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) **MSL, Peak Temp.** - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) **Important Information and Disclaimer**: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.
### TAPE AND REEL INFORMATION

- **Device**: AFE4960YBGR, AFE4960YBGT
- **Package Type**: DSBGA
- **Drawing**: YBG
- **Pins**: 36
- **SPQ**: 3000, 250
- **Reel Diameter**: 330.0 mm
- **Reel Diameter**: 330.0 mm
- **Reel Width**: 12.4 mm
- **A0**: 2.73 mm
- **B0**: 2.73 mm
- **K0**: 0.67 mm
- **P1**: 8.0 mm
- **W**: 12.0 mm
- **Pin1 Quadrant**: Q1

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### TAPE DIMENSIONS

- **K0**: Dimension designed to accommodate the component width
- **B0**: Dimension designed to accommodate the component length
- **K0**: Dimension designed to accommodate the component thickness
- **W**: Overall width of the carrier tape
- **P1**: Pitch between successive cavity centers

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### PACKAGE MATERIALS INFORMATION

- **Pack Materials-Page 1

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*All dimensions are nominal.*

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*All dimensions are nominal*
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).
NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.
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